

REPLACEMENT SHEET

Sheet 1 of 4

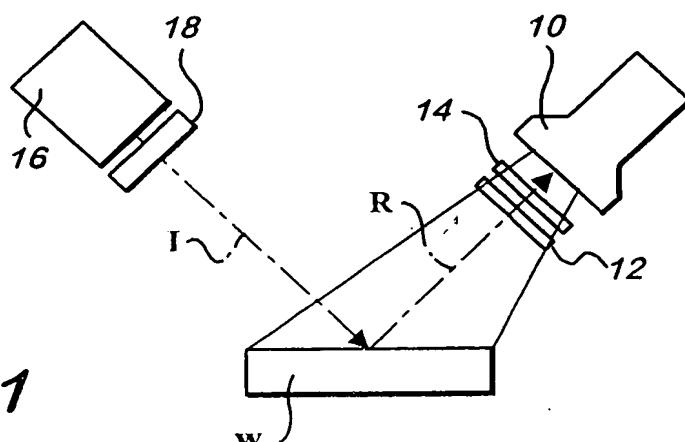


FIG. 1

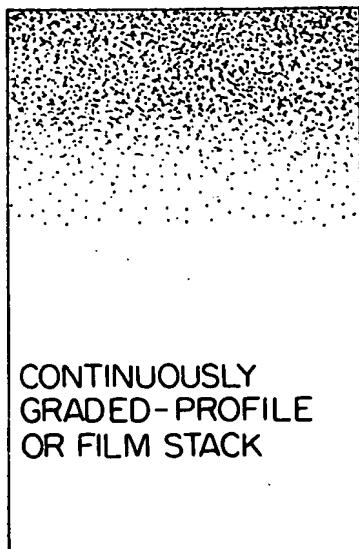
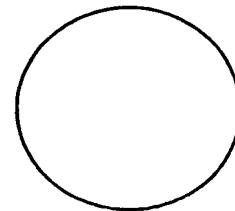
**1. MEASURE
RADIANCE AT P & S
POLARIZATIONS
 R_p AND R_s AT EACH
PIXEL**

**2. SIGNAL
PROCESS
COMPUTE
 $PER = R_p / R_s$
AT EACH PIXEL**

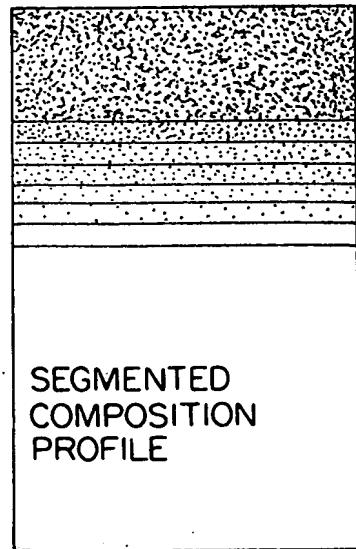
**3. MODEL
COMPUTE
EMISSIVITY
FROM PER**

**4. CALCULATE
TEMPERATURE
AT EACH PIXEL FROM
RADIANCE AND
CALCULATED
EMISSIVITY**

**5. CONSTRUCT MAP
DISPLAY AND EXPORT**



CONTINUOUSLY
GRADED-PROFILE
OR FILM STACK



SEGMENTED
COMPOSITION
PROFILE

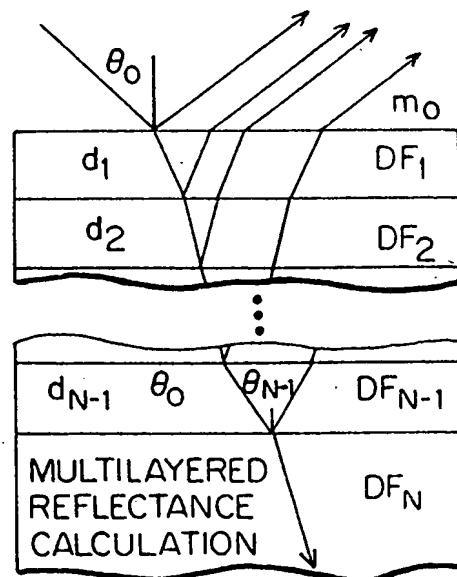


FIG. 3A

FIG. 3B

FIG. 3C

Title: Thermal Imaging For Semiconductor Process Monitoring
Applicants: Rosenthal et al.
Serial No.: 09/199,677
Attorney: Erik Saarmaa
Docket No.: ASX-104
Filed: November 25, 1998
Reg. No.: 56,834

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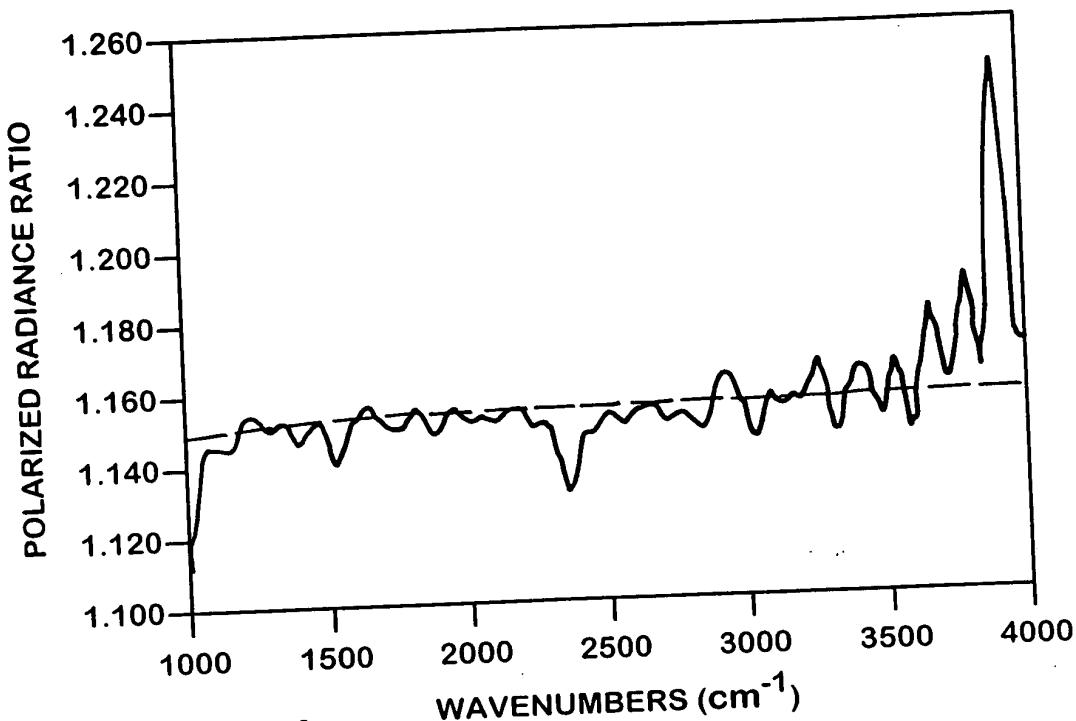


FIG. 4A

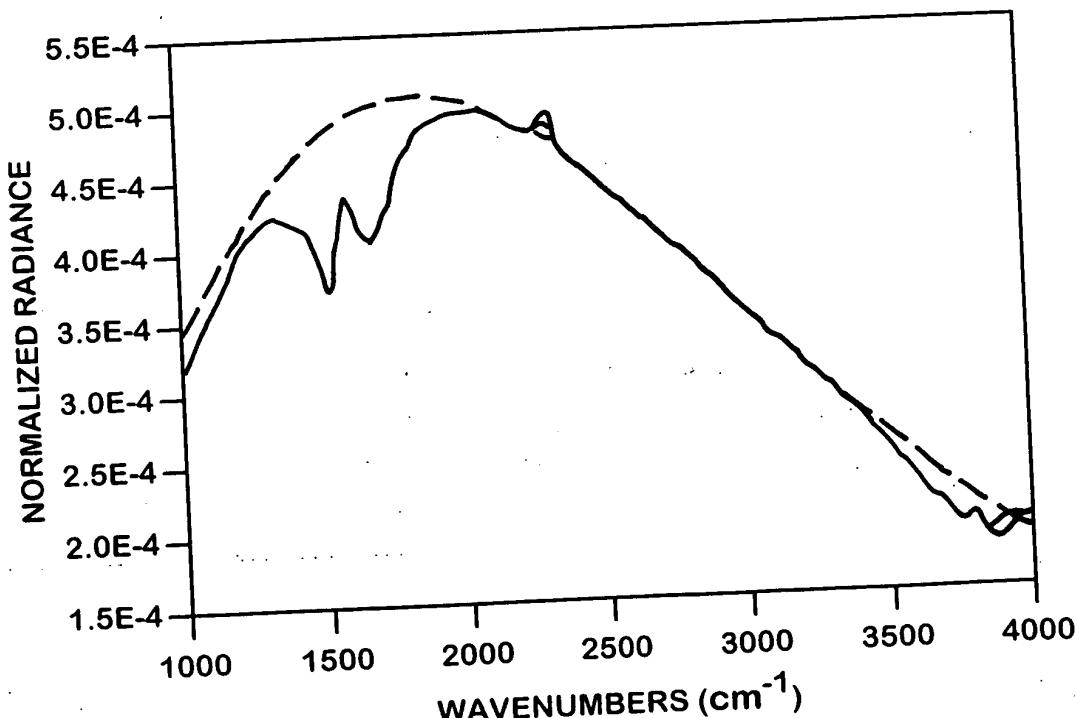


FIG. 4B

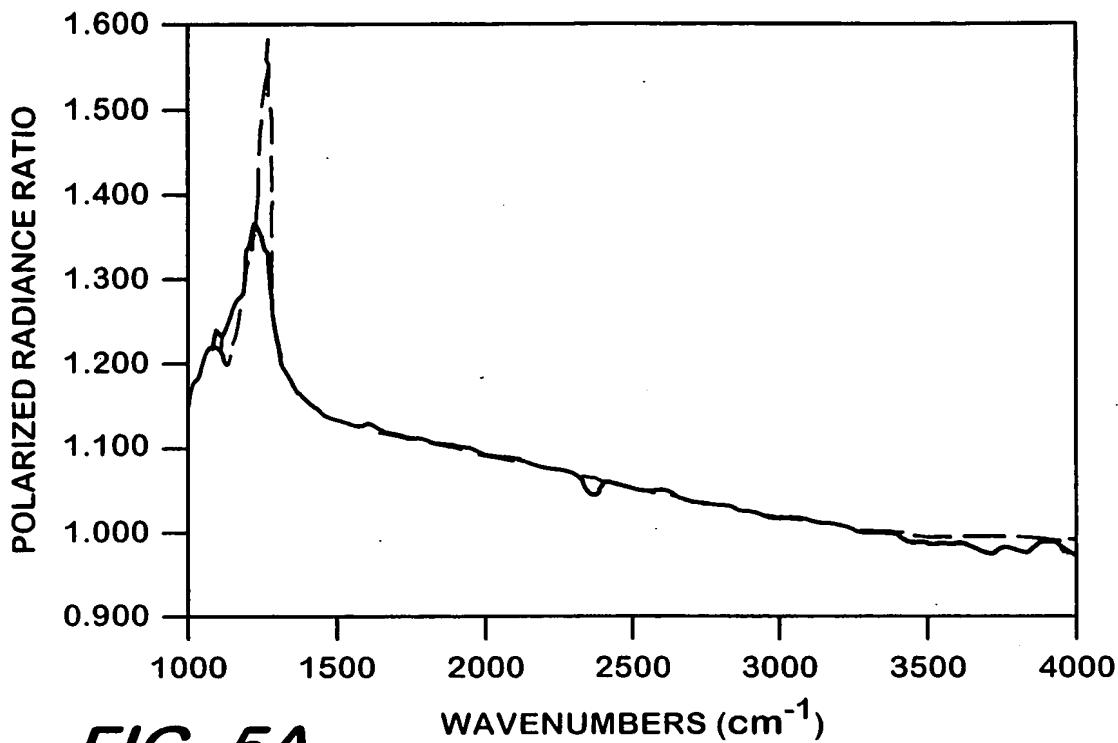


FIG. 5A

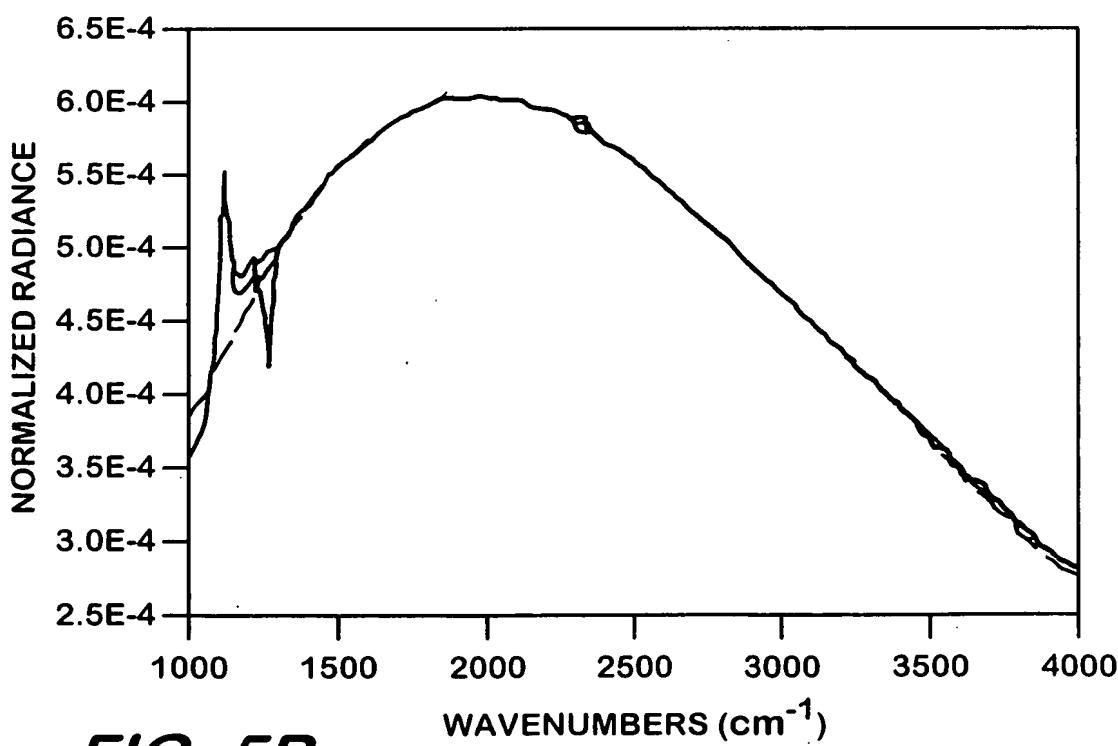


FIG. 5B

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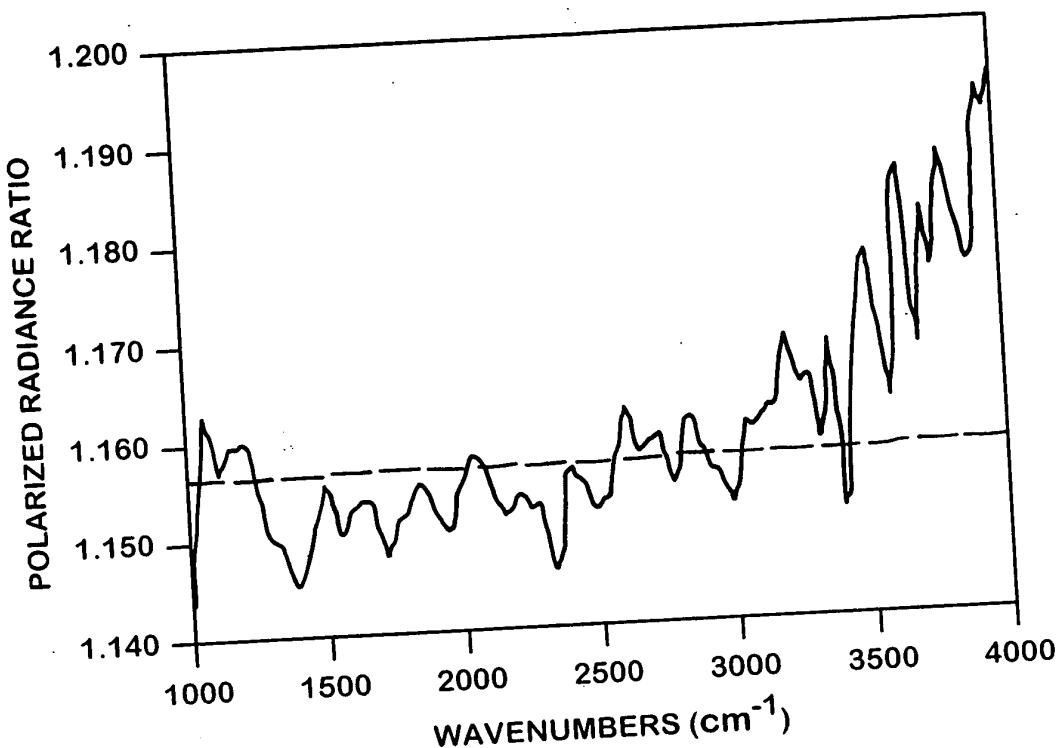


FIG. 6A

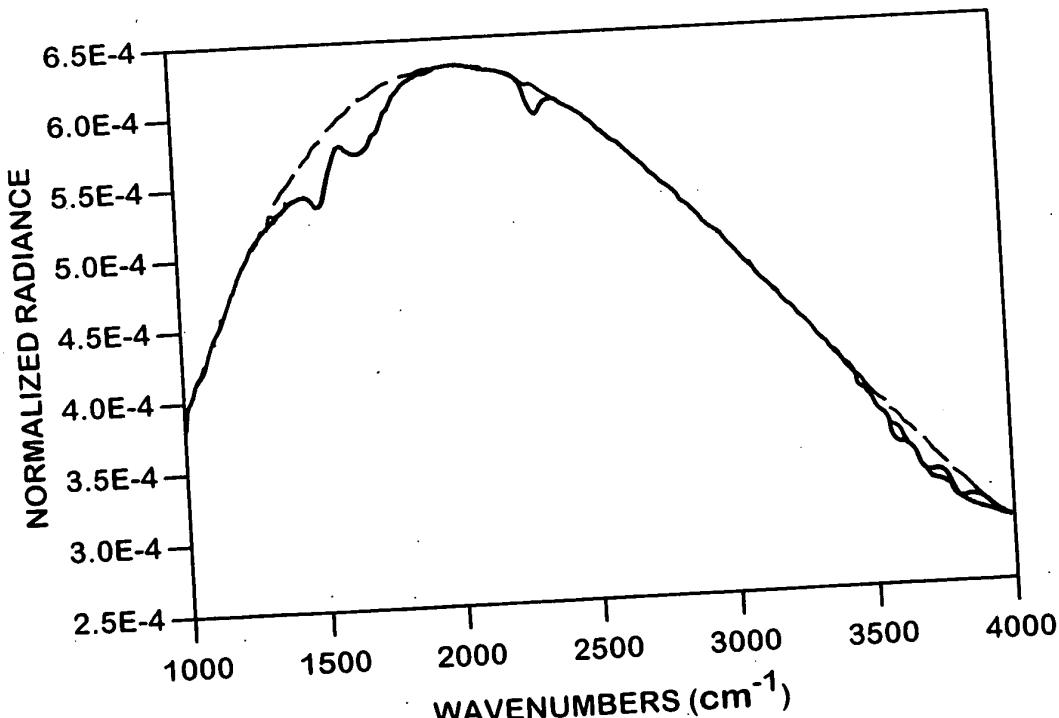


FIG. 6B